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Wang et al.

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(54) **WOOD GRAIN PATTERN FOR SIMULATED WOOD FLOORING PLANKS**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**

USPC **D25/150**

(58) **Field of Classification Search**

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See application file for complete search history.

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(57) **CLAIM**

The ornamental design of a wood grain pattern for simulated wood flooring planks, as shown and described.

DESCRIPTION

The FIGURE is a front elevation view of a wood grain pattern for simulated wood flooring planks.

1 Claim, 1 Drawing Sheet



